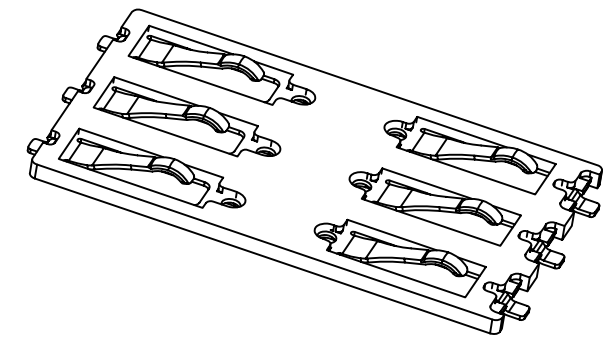
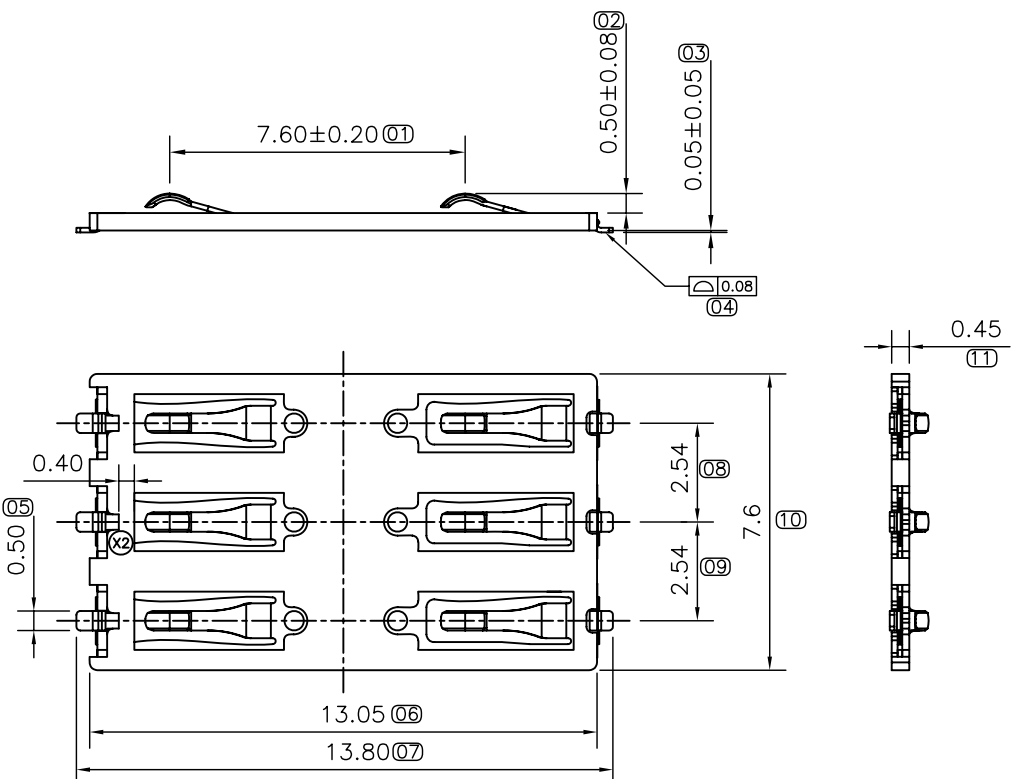
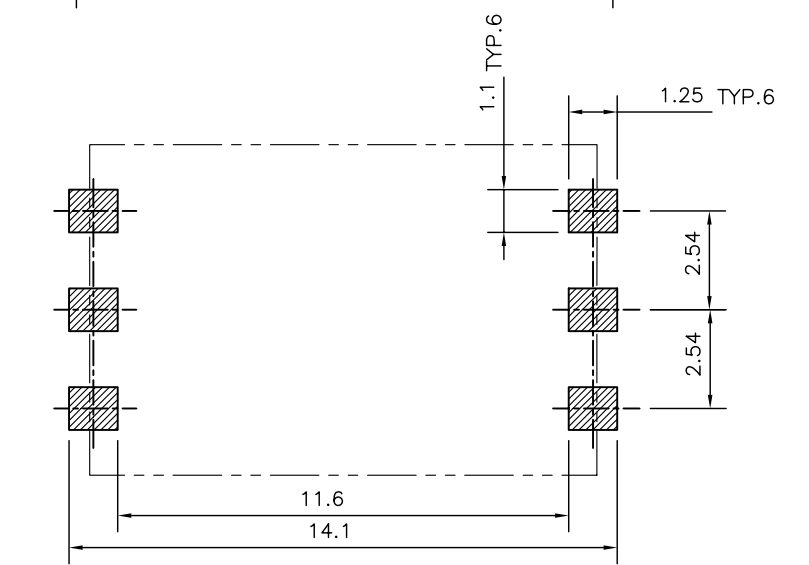


REV	ECN NO	DESCRIPTION	DATE	APPD
x1		BRAN-NEW	2008.04.12	HANSEN
X2	PECN1309011	塑件加胶0.15mm	2013.09.29	TLH



- NOTE:
- HOUSING MATERIAL: THERMAL PLASTIC, COLOR: BLACK;
 - CONTACT MATERIAL: COPPER ALLOY;
 - PLATING:
15u"(0.375um)Min. GOLD PLATING ON CONTACT AREA;
100u"(2.54um)Min. MATTE-TIN PLATING ON SOLDER AREA.
 - PERFORMANCE:
4.1: CONTACT RESISTANCE: 60mOHM Max.
4.2: DIELECTRIC WITHSTANDING VOLTAGE: 200 VAC FOR 1MINUTE;
4.3: INSULATION RESISTANCE: 1000MOHM Min.
4.4: DURABILITY: 5000 TIMES Min.



EXTEND USE		TITLE		FAP	
MICRO SIM CARD 0.5H		MICRO SIM CARD 0.5H		C-1.038A0	
UNIT mm		ASSEMBLY DRAWING		DWG NO	
GENERAL TOLERANCE (11)		MATERIAL APPD 谭林红 2013.09.29		P/N: 1.038A0-006-5R0	
DIMENSION		QTY CHD 谭林红 2013.09.29		SHEET SCALE 1/1	
ANGLES		FINISHED DRN 黄文珠 2013.09.29		SCALE 1:1	
. ±0.30	. ±3'			REV X2	
.0 ±0.25	.0 ±2'				
.00 ±0.20	.00 ±1'				
.000 ±0.10					